

30 MAY 2001

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

2 / 4rel. andt.  
A  
E. Willis

Yoshio YANASE et al.

Attn: BOX PCT 11-13-01

Serial No. NEW

Docket No. 2001-0615A

Filed May 30, 2001

METHOD FOR INSPECTING  
SEMICONDUCTOR WAFER SURFACE  
[Corresponding to PCT/JP00/07147  
Filed October 13, 2000]

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PRELIMINARY AMENDMENTAssistant Commissioner for Patents,  
Washington, DC 20231

Sir:

Prior to examination of the above-referenced U.S. patent application please amend the application as follows:

IN THE CLAIMS

Please amend the claims as follows:

A 1

3. (Amended) A method for inspecting a semiconductor wafer surface according to Claim 1, wherein a laser surface inspection apparatus having at least two light optics to one incidence is used as a laser surface inspection apparatus.

4. (Amended) A method for inspecting a semiconductor wafer surface according to Claim 1, wherein the semiconductor wafer is an epitaxial semiconductor wafer.